

Ultra Fast Avalanche Sinterglass Diode

Features

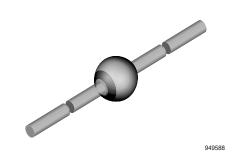
- Glass passivated junction
- · Hermetically sealed package
- Low reverse current
- Soft recovery characteristics
- · Very fast reverse recovery time
- Low reverse recovery peak current

Applications

Ultra fast rectification diode for switching mode power supplies

Mechanical Data

Case: Sintered glass case, SOD 64 **Terminals:** Plated axial leads, solderable per MIL-STD-750, Method 2026



Polarity: Color band denotes cathode end **Mounting Position:** Any **Weight:** 860 mg, (max. 1000 mg)

Parts Table

Part	Type differentiation	Package
BYW178	V _R = 800 V; I _{FAV} = 3 A	SOD64

Absolute Maximum Ratings

T_{amb} = 25 °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Reverse voltage = Repetitive peak reverse voltage	see electrical characteristics		V _R = V _{RRM}	800	V
Peak forward surge current	t _p = 10 ms, half sinewave		I _{FSM}	80	А
Repetitive peak forward current			I _{FRM}	15	А
Average forward current			I _{FAV}	3	А
Junction and storage temperature range			$T_j = T_{stg}$	- 55 to + 175	°C
Non repetitive reverse	I _{(BR)R} = 0.4 A		E _R	20	mJ

Maximum Thermal Resistance

 $T_{amb} = 25 \ ^{\circ}C$, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Junction lead	I = 10 mm, T _L = constant		R _{thJL}	25	K/W
Junction ambient	on PC board with spacing 37.5 mm		R _{thJA}	70	K/W

Document Number 86047 Rev. 5, 07-Jan-03



Electrical Characteristics

 $T_{amb} = 25 \ ^{\circ}C$, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Min	Тур.	Max	Unit
Forward voltage	I _F = 3 A		V _F			1.9	V
Reverse current	V _R = V _{RRM}		I _R			1	μA
	$V_R = V_{RRM}, T_j = 100 \ ^\circ C$		I _R			20	μA
Reverse recovery current	$I_F = 1 \text{ A}, \text{ di}_F/\text{dt} \le$ - 50 A/µs, V _{Batt} = 200 V		I _{RM}		2.2		A
Reverse recovery time	I_{F} = 1 A, di _F /dt \leq - 50 A/µs, V _{Batt} = 200 V, i _R = 0.25 x I _{RM}		t _{rr}		50		ns
Reverse recovery time (JEDEC)	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_R = 0.25 \text{ A}$		t _{rr}			60	ns

Typical Characteristics (T_{amb} = 25 °C unless otherwise specified)

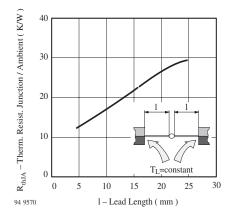


Figure 1. Typ. Thermal Resistance vs. Lead Length

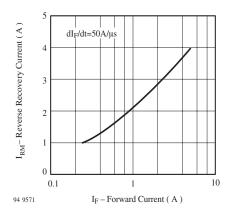


Figure 2. Typ. Reverse Recovery Current vs. Forward Current

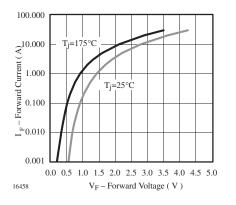


Figure 3. Forward Current vs. Forward Voltage

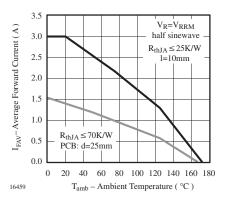


Figure 4. Max. Average Forward Current vs. Ambient Temperature



BYW178

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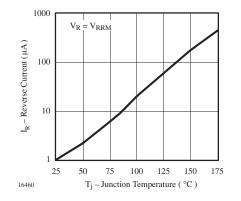


Figure 5. Reverse Current vs. Junction Temperature

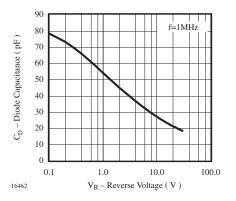


Figure 7. Diode Capacitance vs. Reverse Voltage

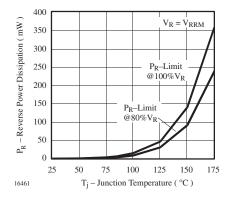


Figure 6. Max. Reverse Power Dissipation vs. Junction Temperature

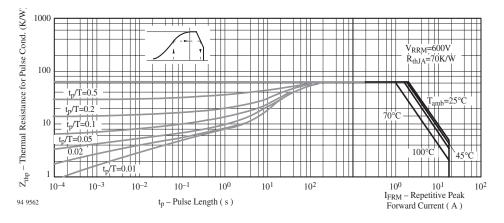
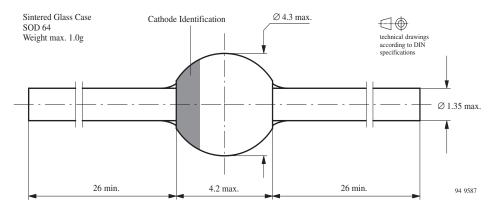


Figure 8. Thermal Response

Document Number 86047 Rev. 5, 07-Jan-03



Package Dimensions in mm





Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operatingsystems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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